



SOT909-1

plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 4 x 4 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON8
Package type industry code	HVSON8
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-229
Mounting method type	S (surface mount)
Issue date	28-9-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	3.9	-	4	4.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	8	-	

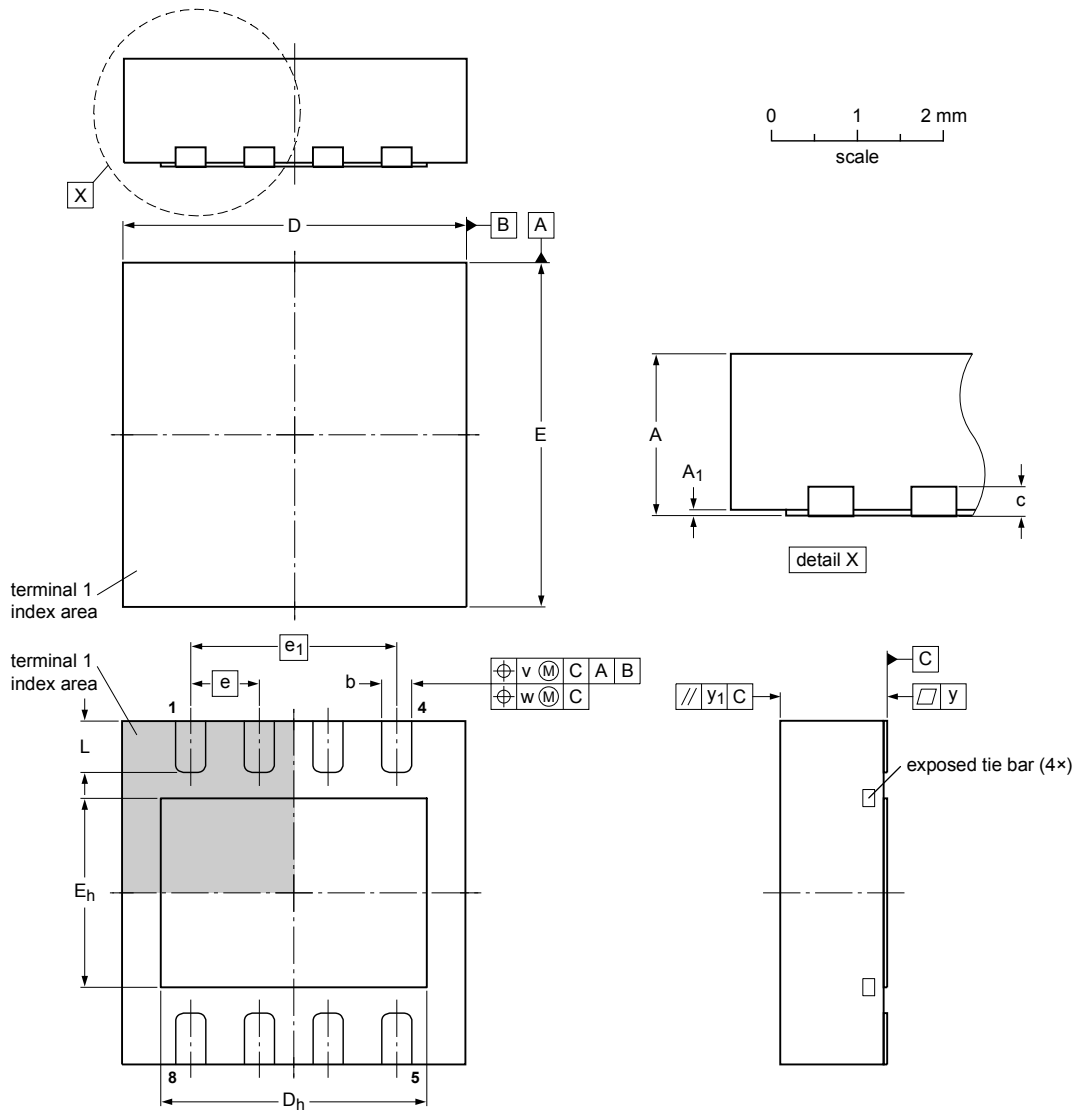


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2. Package outline

HVSON8: plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 4 x 4 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max.	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	L	v	w	y	y ₁
mm	1	0.05 0.00	0.4 0.3	0.2	4.1 3.9	3.25 2.95	4.1 3.9	2.35 2.05	0.8	2.4	0.65 0.40	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT909-1		MO-229			05-09-26 05-09-28

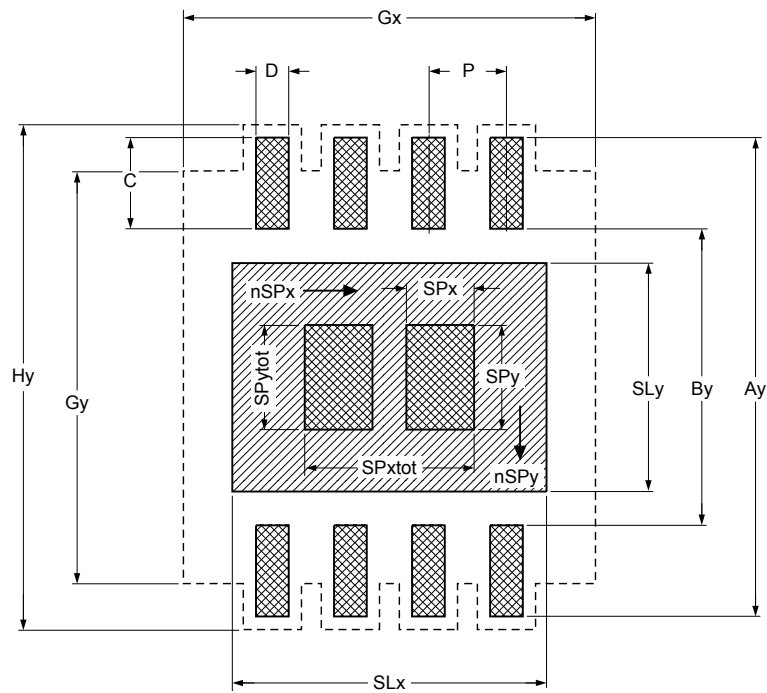
Fig. 1. Package outline HVSON8 (SOT909-1)




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3. Soldering

Footprint information for reflow soldering of HVSON8 package

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-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

DIMENSIONS in mm

P	A _y	B _y	C	D	SL _x	SL _y	SP _{xtot}	SP _{ytot}	SP _x	SP _y	G _x	G _y	H _y	nSP _x	nSP _y
0.8	4.95	3.05	0.95	0.35	3.25	2.35	1.75	1.1	0.7	1.1	4.25	4.25	5.2	2	1
Issue date	12-02-23 13-02-25														

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Fig. 2. Reflow soldering footprint for HVSON8 (SOT909-1)

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mm

4. Legal information

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